



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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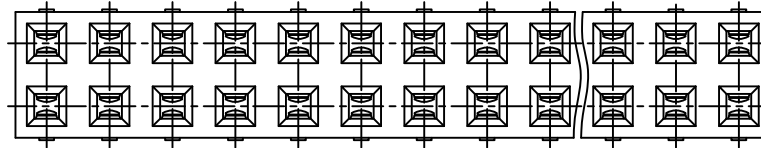
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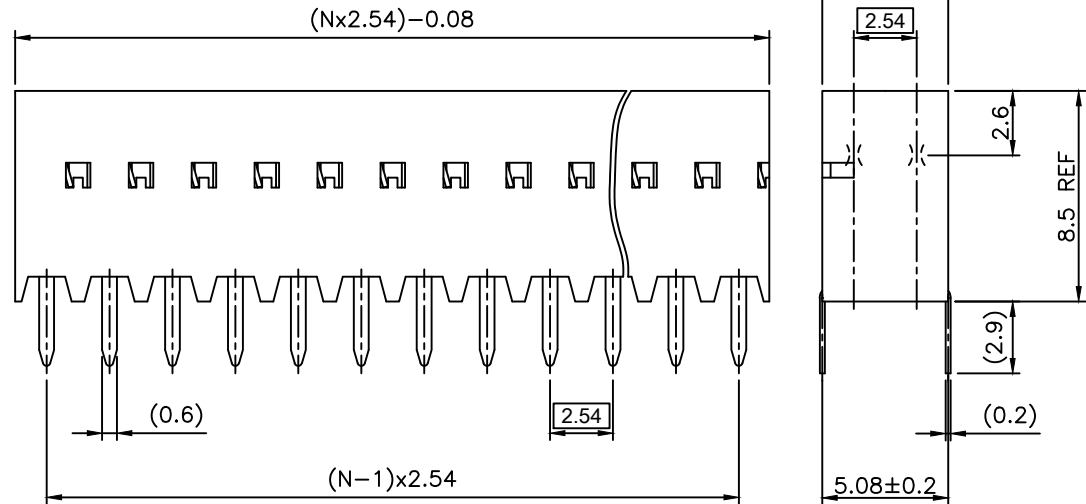
PRODUCT NUMBER  
89891-YXXXLF

- RoHS COMPATIBLE, SEE NOTE 6
- OPTIONAL LETTER  
H: HIGH TEMPERATURE PRODUCT.
- NUMBER OF POSITIONS PER ROW : 02 TO 50.
- PLATING CODE  
3= 0.76µm GOLD ON CONTACT AREA.  
2µm MIN MATTE TIN ON TAIL.  
4= 2µm MIN MATTE TIN FULL PLATED  
1.27µm Ni MIN UNDERPLATING



NOTES:

- 1 - HOUSING MAT'L: THERMOPLASTIC GLASS FILLED  
FLAME RETARDANT PER UL 94 V-0  
LOW TEMPERATURE: COLOR BLUE  
HIGH TEMPERATURE: COLOR GREY.
- 2 - TERMINAL MATERIAL: PHOSPHOR BRONZE.
- 3 - 2 UP TO 4 POSITIONS PRODUCT PACKED IN PLASTIC BOX.  
5 UP TO 50 POSITIONS PRODUCT PACKED IN TUBE.
- 4 - TO DETERMINE DIMENSIONS:  
N = NUMBER OF POSITIONS  
EXAMPLE: 8 POS:  $(N \times 2.54) - 0.08 = 20.24$  mm
- 5 - HE13 PRINTING ON 89891-3XX PRODUCT.
- 6 - RoHS COMPATIBLE PRODUCT SPECIFICATIONS
  - a - PLATING:
    - "LF" MEANS THE PRODUCT IS LEAD-FREE,  
2µm MINIMUM MATTE TIN OVER 1.27µm  
MINIMUM NICKEL UNDERPLATE.
  - b - MANUFACTURING PROCESS COMPATIBILITY
    - THE HOUSING WILL WITHSTAND EXPOSURE TO  
260°C ±5°C SOLDER BATH TEMPERATURE FOR  
5 SECONDS IN A WAVE SOLDER APPLICATION  
WITH A 1.6mm MIN THICK CIRCUIT BOARD.
  - c - LABELING:
    - MEETS PACKAGING SPECS AS PER GS-14-920
  - d - LEGAL STATEMENT: SEE GS-47-0004



mat'l. code SEE NOTE 1		surface ISO 1302 ✓ ISO 406 ISO 1101		tolerance ISO 406 ISO 1101		projection mm		product family DUBOX	
lfr		ecn no		dr		date		title	
F		F10308		GCO		01.05.10		BtB RECEIPT. VERT DR TMT	
G		F04-0347		DLE		04.09.23			
H		F05-0230		DLE		05.08.08			
J		F06-0204		DLE		06.06.21			
K		F07-0156		DLE		07.03.16		sheet 1 of 2	
L		B-19123		LMU		14.10.21		size A3	
M		F-28430		DDE		17.11.09		type CUSTOMER Drawing	
sheet index		revision		M		D			
		sheet		1		2			

2

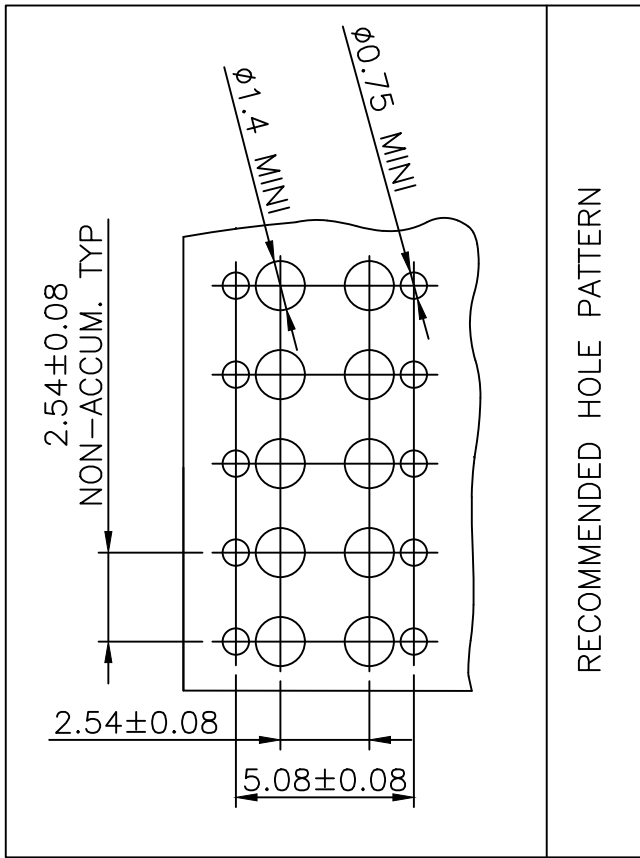
1

A

B

C

D



RECOMMENDED HOLE PATTERN

Fconnect.com



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mat'l. code SEE SHEET 1		surface ISO 1302 ✓	tolerance ISO 406 ISO 1101	projection 	product family DUBOX
ltr	ecn no	dr	date	mm	title BtB RECEIPT. VERT DR TMT
A	F04-0347	DLE	04.09.23	scale 5:1	dwg no sheet 2 of 2
B	F05-0230	DLE	05.08.08		size A4
C	F06-0204	DLE	06.06.21		89891
D	F07-0156	DLE	07.03.16		CUSTOMER
		engr	P NIZZI		Drawing
		chr	D LE		
		appd	P NZ		
sheet index	revision sheet				